

N-Channel Super Junction Power MOSFET II

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

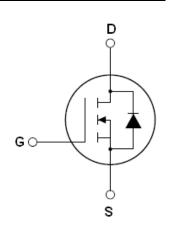
Features

- •New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS} @T _{jmax}	650	V
R _{DS(ON)} MAX	1200	mΩ
ID	4	А



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE60R1K2Z	TO-92	NCE60R1K2Z



TO-92

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	Vds	600	V
Gate-Source Voltage (VDs=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	4	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	2.5	А
Pulsed drain current (Note 1)	DM (pluse)	12	А
Maximum Power Dissipation(Tc=25°C)	PD	4	W
Derate above 25°C		0.03	W/°C
Single pulse avalanche energy (Note2)	Eas	130	mJ
Avalanche current ^(Note 1)	I _{AR}	2	А
Repetitive Avalanche energy , t_{AR} limited by $T_{j\text{max}}$ (Note 1)	E _{AR}	0.2	mJ



Parameter	Symbol	Value	Unit		
Drain Source voltage slope, V_{DS} \leq 480 V,	dv/dt	50	V/ns		
Reverse diode dv/dt, $V_{DS} \leqslant 480 V,I_{SD} < I_D$	dv/dt	15	V/ns		
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55+150	°C		
Table 2. Thermal Characteristic					
Parameter	Symbol	Value	Unit		
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	31	°C /W		
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	180	°C /W		

Table 3. Electrical Characteristics (TA=25 $^\circ\!\!\mathrm{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states		·				
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	600			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			50	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±30V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2A		1000	1200	mΩ
Dynamic Characteristics						
Forward Transconductance	g fs	V _{DS} = 20V, I _D = 2.5A		4		S
Input Capacitance	C _{lss}			280		PF
Output Capacitance	C _{oss}	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		26		PF
Reverse Transfer Capacitance	C _{rss}			2.3		PF
Total Gate Charge	Qg)/ _400)// _44		6.5	10	nC
Gate-Source Charge	Q _{gs}	V_{DS} =480V,I _D =4A,		1.3		nC
Gate-Drain Charge	Q_gd	V _{GS} =10V		2.5		nC
Intrinsic gate resistance	R _G	f = 1 MHz open drain		2.5		Ω
Switching times			•			
Turn-on Delay Time	t _{d(on)}			6		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =2.5A,		3		nS
Turn-Off Delay Time	t _{d(off)}	R _G =20Ω,V _{GS} =10V		48	60	nS
Turn-Off Fall Time	t _f			8	15	nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I _{SD}	T _05%O			4	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			12	А
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =4A,V _{GS} =0V		1	1.3	V
Reverse Recovery Time	t _{rr}			150		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I⊧=4A,di/dt=100A/µs		0.85		uC
Peak reverse recovery current	I _{rrm}			11		А

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25\Omega



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

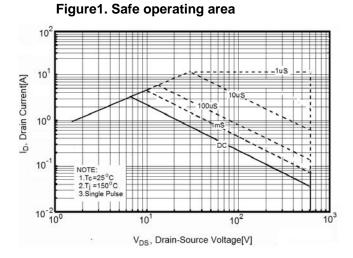


Figure3. Output characteristics

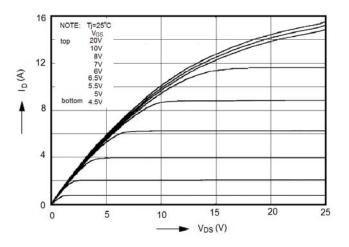


Figure5. Static drain-source on resistance

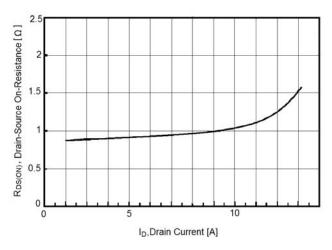


Figure2. Source-Drain Diode Forward Voltage

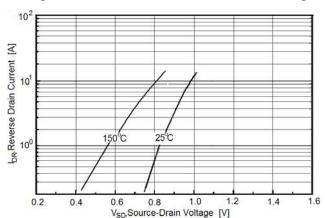


Figure4. Transfer characteristics

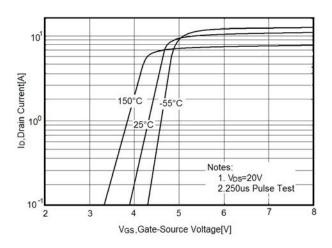


Figure6. R_{DS(ON)} vs Junction Temperature

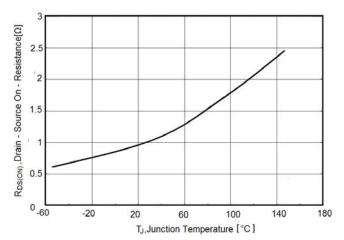
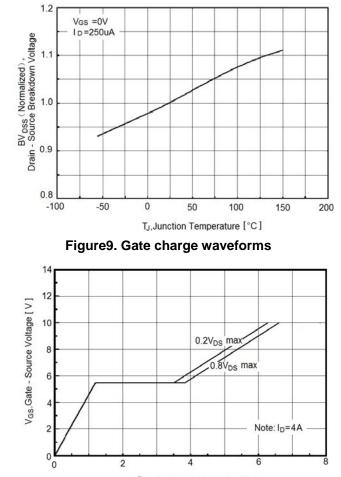




Figure 7. BV_{DSS} vs Junction Temperature

Figure8. Maximum I_D vs Junction Temperature



Q_G, Total Gate Charge [nC]

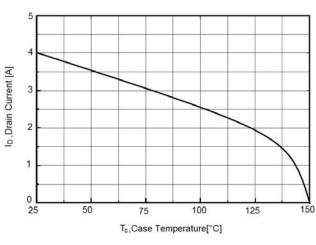
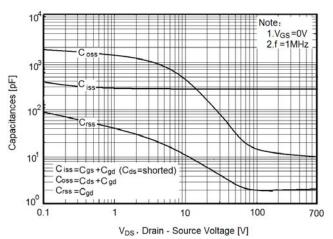


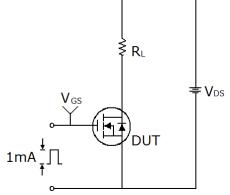
Figure10. Capacitance

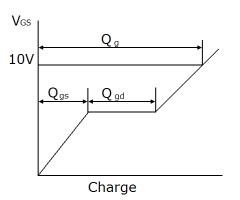




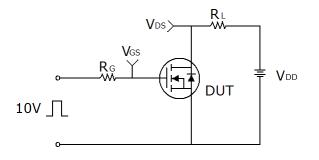
Test circuit

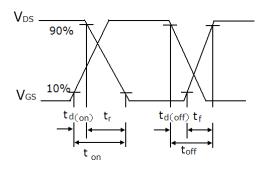
1) Gate charge test circuit & Waveform



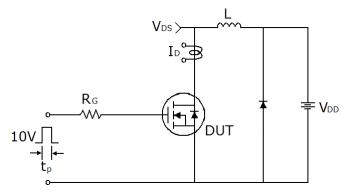


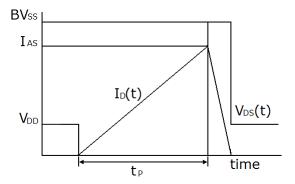
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

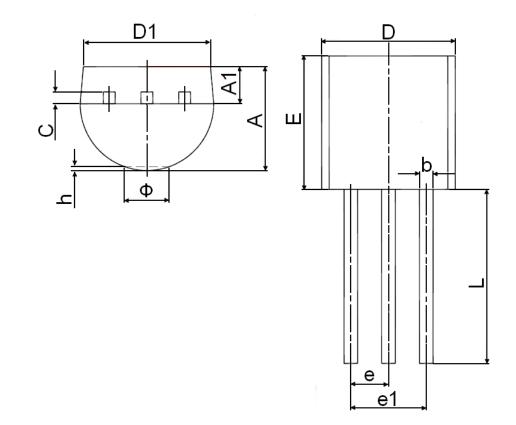








TO-251 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	3.300	3.700	0.130	0.146	
A1	1.100	1.400	0.043	0.055	
b	0.380	0.550	0.015	0.022	
с	0.460	0.580	0.018	0.023	
D	4.400	4.700	0.173	0.185	
D1	3.430		0.135		
E	4.300	4.700	0.169	0.185	
e	1.27	1.270TYP)TYP	
e1	2.440	2.640	0.096	0.104	
L	14.100	14.500	0.555	0.571	
Φ		1.600		0.063	
h	0.000	0.380	0.000	0.015	



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